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## PATENT ABSTRACTS OF JAPAN

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**(54) HIGH-TEMPERATURE SOLDER**

of soldering.

(57) Abstract:

**PURPOSE:** To provide the high-temp. solder which obviates the remelting of the soldered part in a hybrid IC at the time of molding the hybrid IC with a resin and assembling the IC into electronic appliances and does not generate the silver suffering in circuits at the time

**CONSTITUTION:** This high-temp. solder consists essentially of Pb, is added with 8 to 14wt.% Sn and 8 to 10wt.% Sb and is added with  $\leq$ 2wt.% Ag in order to prevent the silver suffering. This solder has  $\geq$ 230°C solidus line temp. and  $\leq$ 260°C soldering temp. and is, therefore, suitable for double deposition of soldering and has less thermal influence on parts.

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